

Figure 1. Schematic for thermal Cu ALE based on (A) oxidation by O₂ or O₃ and (B) oxide spontaneous etching using acetylacetone (Hacac).

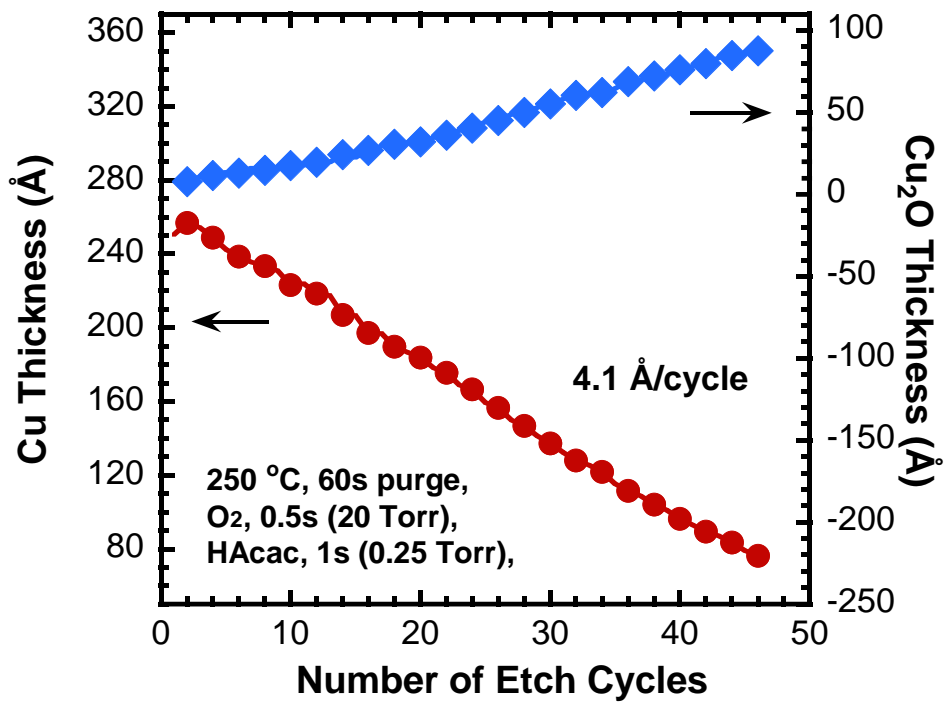


Figure 2. Cu ALE at 250 °C using sequential exposures of O₂ and Hacac.